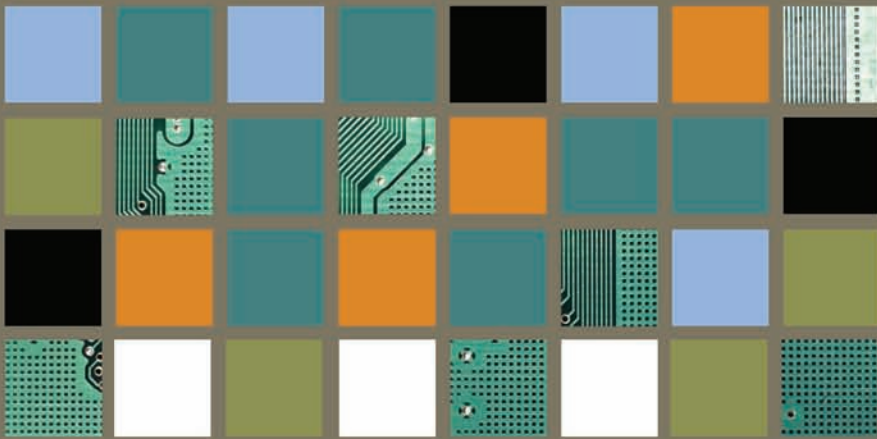
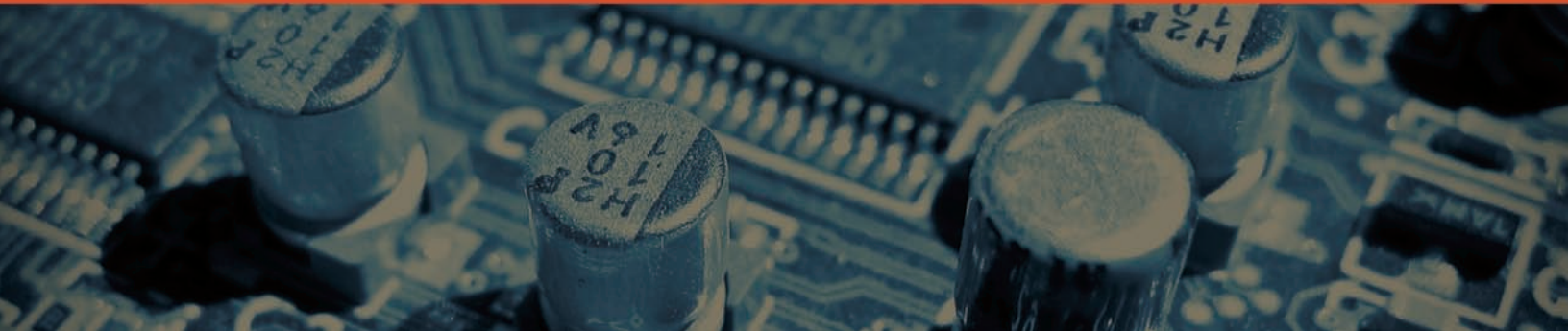


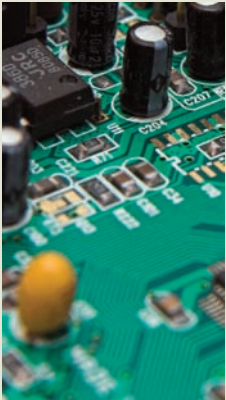


# 2008 FALL ENGINEERING SUMMIT



OCTOBER 6 - 9, 2008 SALT LAKE CITY, UT





Our **2008 Fall Engineering Summit** is a four-day program designed to inform and connect leaders in the electronics components industry. NEW this year! A series of exciting and relevant general sessions and participation activities. It's your best chance to network with engineering leaders across the electronic components industry as they consider, develop and finalize crucial EIA Standards. EIA Standards sets the precedent for safety, interoperability and performance optimization in an effective and efficient environment.

**Don't miss this opportunity to:**

- Contribute to your company's views on emerging standards
- Participate in streamlined standards development
- Promote new EIA Standards critical to your company's business
- Interface with industry experts on the issues that shape and define the market

Be there to influence the technical course of the electronic components industry. You can find out who is meeting and the cost to attend by viewing the program. Don't delay, register today!

## GENERAL SESSIONS

**TUESDAY • OCTOBER 7 • 8:00 AM – 12:00 NOON**

**8:00 am – 10:00 am** William Cutler  
Plant Manager, Ceramics Facility  
Bourns, Inc., Logan, UT

### GENERAL SESSION 1

#### “Competing in a World-Wide Market in the 21st century.”

*Are your products and services just staying competitive or leading the industry?*

- Competition in the future
- How to beat the competition
  - Quality and Reliability improvements in manufacturing processes.
  - Customer Satisfaction in Service
- Summary
- Q & A

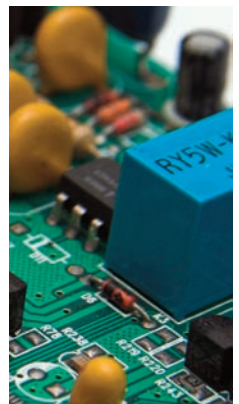
**10:00 am – Noon** Robert C. Pfahl, Jr.  
Vice President of Operations  
International Electronics Manufacturing Initiative (iNEMI)  
Herndon, VA

### GENERAL SESSION 2

#### “A Snapshot of New Findings on Passive Components in the 2009 iNEMI Roadmap”

Topics include :

- Business Issues
- Unintended Consequences of Green
- Technology Trends & Needs
  - capacitor types
  - inductors & transformers
  - current protection
- Alternative Technologies (embedded passives)



WEDNESDAY • OCTOBER 8TH • 8:00 – 10:00 AM WORKSHOP

**GENERAL SESSION 3**

**“Tape & Reel Packaging: Review of Changes to Industry Standards”**

**Presented By:**

- Bill Aldeen, President of Nu-Way Electronics, and a member of the “Automated Component Handling” Committee of the Electronic Industries Alliance (EIA).
- Scott Carter, Vice President of Tek Pak and chairman of the “Automated Component Handling” Committee.

**Summary:**

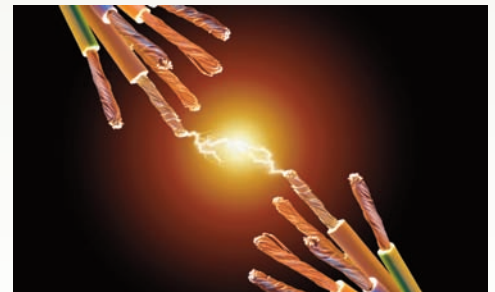
In 2008, EIA issued new versions of the standards for Surface Mount Tape & Reel Packaging (EIA-481) and Radial Tape & Reel Packaging (EIA-468). The revised standards incorporate major innovations and will have significant impact on the producers and users of electronic components. The program will review both new standards and highlight the changes from previous versions. The presentation will cover the development and creation of new standards and provide a question and answer session.

**Topics Include:**

- Orientation of SMT devices in carrier tape
- Measurement of “camber” in SMT carrier tape
- Overview of Radial standard, which has been completely rewritten
- Radial lead spacing and pitch options
- Seek suggestions for future changes to standards

**Who Should Attend:**

- Manufacturing engineers and machine operators
- Buyers of taped components
- Design engineers in SMT and through-hole technology
- Component manufacturers
- Manufacturers of packaging materials, such as carrier tapes, adhesive tapes, and reels



**TRAVEL & ACCOMODATIONS**

**Red Lion Hotel**

An advance deposit or credit card guarantee for the first night's room and tax is due by September 19, 2008. Individuals must identify themselves as part of ECA at the time of making reservations in order to be eligible for the special group rate. Please call (801) 521-7373 to make reservations.

**Each individual is responsible for making their own reservations.**

**Red Lion Hotel**  
 161 West 600 South  
 Salt Lake City, UT 84101  
 Ph: 801.521.7373

**Room Rates: \$119**  
**Hotel Cutoff Date: September 19, 2008**  
**Reservations Deadline: September 19, 2008**  
**Hotel Website: <http://redlion.rdln.com>**

**REGISTRATION** (\*required fields)

First Name: \* \_\_\_\_\_ Last Name: \* \_\_\_\_\_  
 Company: \* \_\_\_\_\_ Title: \_\_\_\_\_  
 Address 1: \* \_\_\_\_\_  
 Address 2: \_\_\_\_\_  
 City: \* \_\_\_\_\_ State: \* \_\_\_\_\_ Zip/Postal Code: \* \_\_\_\_\_  
 Phone: \* \_\_\_\_\_ Fax: \_\_\_\_\_ Email: \* \_\_\_\_\_  
 ECA Member:  Yes  No  I would like more information

**Participants are encouraged to register online at [www.eacus.org](http://www.eacus.org)**

**COMMITTEE MEETINGS & ACTIVITIES**

*Please select all committee meetings and activities that you plan to attend:*

- |  |   |   |  |
|--|---|---|--|
| <input type="checkbox"/> ACH Automated Component Handling    | <input type="checkbox"/> General Session 1 "Competing in a World-Wide Market in the 21st Century"                       | <input type="checkbox"/> P-1 Resistive Devices                    | <input type="checkbox"/> P-14 Overcurrent Protection Devices |
| <input type="checkbox"/> CE-2.0 National Standards Committee | <input type="checkbox"/> General Session 2 "A Snapshot of New Findings on Passive Components in the 2009 iNEMI Roadmap" | <input type="checkbox"/> P-2.1 Ceramic Dielectric Capacitors      | <input type="checkbox"/> S-1 General Session                 |
| <input type="checkbox"/> Ceramic Working Lunch               | <input type="checkbox"/> General Session 3 "Tape & Reel Packaging: Review of Changes to Industry Standards"             | <input type="checkbox"/> P-2.2 Aluminum, Film and Mica Capacitors | <input type="checkbox"/> STC Soldering Technology Committee  |
| <input type="checkbox"/> ECA Dinner                          |   | <input type="checkbox"/> P-2.5 Tantalum Capacitors                | <input type="checkbox"/> STPC                                |
| <input type="checkbox"/> ECA Luncheon                        |   | <input type="checkbox"/> P-3 Inductive Components                 | <input type="checkbox"/> Tantalum Working Group              |
|  |   | <input type="checkbox"/> P-4 Mechanical Outlines                  |  |
|  |   | <input type="checkbox"/> P-10 Integrated Passive Devices          |  |

**FEES**

**Full Summit Registration (includes registration for all meetings, meals, receptions, and presentations)**

**Members:** \$250/person  
 (\$275 after September 19th)  
**Non-Members:** \$300/person  
 (\$350 after September 19th)

**Attend ONE Committee Meeting Only Attendance at no charge (does not include meals)**

Please specify day(s):  
 Mon.  Tues.  Wed.  Thurs.  
 Tuesday Dinner - \$60.00 Guest/Spouse fee  
 \$\_\_\_\_\_ TOTAL

**Attend ONE Full Day of Meetings Only \$100**

Please specify day(s):  
 Mon.  Tues.  Wed.  Thurs.

**PAYMENT METHOD**

- VISA  MasterCard  American Express  Check

Card Holder Name: \_\_\_\_\_  
 Card Number: \_\_\_\_\_ CVV (four digit code on the back of your card) \_\_\_\_\_  
 Expiration Date: \_\_\_\_\_ Month \_\_\_\_\_ Year

**For payment by check, mail this form to:**

ECA Spring Summit  
 c/o Cecelia Yates  
 2500 Wilson Blvd.  
 Suite 310  
 Arlington, VA 22201

**You may also fax this form to 703.875.8908.**

Questions? Please contact Cecelia Yates at 703.907.8026 or [cyates@ecaus.org](mailto:cyates@ecaus.org).

# FALL ENGINEERING SUMMIT

## Schedule-at-a-Glance

### MONDAY • OCTOBER 6

8:30 am	–	4:00 pm	Registration
9:00 am	–	5:00 pm	CE-2.0 National Connector Standards (part 1)
9:00 am	–	Noon	Ceramic Working Group
Noon	–	1:00 pm	Box Lunch
1:00 pm	–	2:30 pm	P-14 Overcurrent Protection Devices
2:30 pm	–	4:00 pm	Tantalum Working Group
5:00 pm	–	8:00 pm	Welcome Reception

### TUESDAY • OCTOBER 7

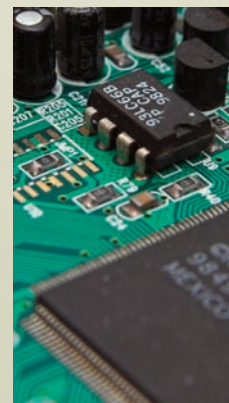
7:30 am	–	4:30 pm	Registration
8:00 am	–	Noon	<b>General Session 1 &amp; 2</b>
8:00 am	–	10:00 am	(1) <b>Competing in a World-wide Market in the 21st Century</b> William Cutler, Bourns
10:00 am	–	Noon	(2) <b>A Snapshot of New Findings on Passive Components in the 2009 iNEMI Roadmap</b> Robert C. Pfahl, Jr., iNEMI
Noon	–	1:30 pm	Awards Luncheon
1:30 pm	–	4:30 pm	CE-2.0 (part 2)
1:30 pm	–	4:30 pm	S-1 General Session
4:30 pm	–	5:30 pm	P-10 Integrated Passive Devices
6:00 pm	–	9:00 pm	Reception/Dinner

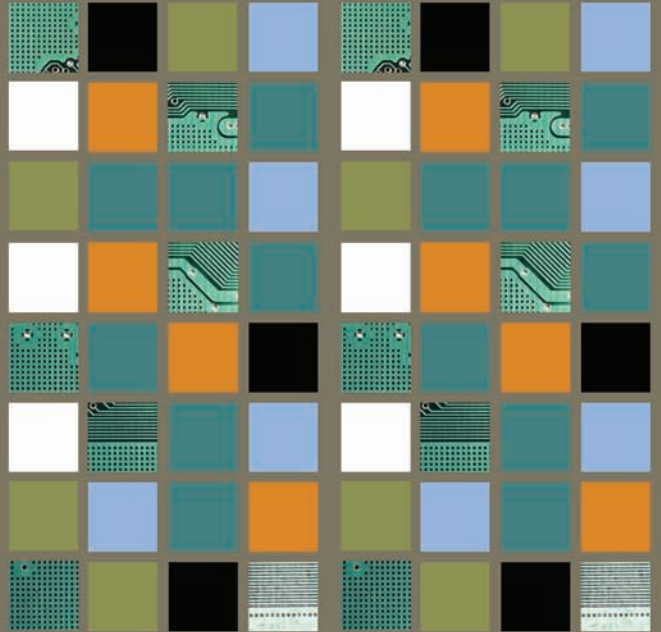
### WEDNESDAY • OCTOBER 8

7:30 am	–	Noon	Registration
8:00 am	–	10:00 am	<b>General Session 3</b> <b>Tape &amp; Reel Packaging: Review of Changes to Industry Standards</b> Bill Aldeen, Nu-Way Electronics & Scott Carter, Tek-Pak
10:00 am	–	11:00 am	P-1 Resistive Devices
10:00 am	–	Noon	Soldering Technology Committee (part 1)
11:00 am	–	Noon	P-2.2 Aluminum, Film and Mica Capacitors
Noon	–	1:30 pm	Lunch (Working Lunch for P-2.1 Ceramic Dielectric Capacitors)
1:30 pm	–	2:30 pm	Soldering Technology Committee (part 2)
1:30 pm	–	2:30 pm	P-3 Inductive Components
2:30 pm	–	3:30 pm	P-2.5 Tantalum Capacitors
3:30 pm	–	5:30 pm	P-4 Mechanical Outlines (part 1)
5:30 pm	–	6:30 pm	Standards & Technology Policy Council

### THURSDAY • OCTOBER 9

8:00 am	–	Noon	Automated Component Handling
8:00 am	–	10:00 am	P-4 Mechanical Outlines (part 2, if needed)





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**ELECTRONIC COMPONENTS ASSOCIATION**

2500 WILSON BOULEVARD, SUITE 310  
ARLINGTON, VA 22201

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